

Appl. No. 09/844,097

Listing of Claims:

This listing of claims replaces all prior versions and listing of claims in the patent application.

Claim 1. (Currently Amended) A flexible printed circuit board comprising a base film; a base film side adhesive layer provided on the base film; a metal foil layer on which pattern circuit is formed, provided on the base film side adhesive layer; and a cover layer side adhesive layer provided on the metal foil layer,

wherein at least one of the base film side adhesive layer and the cover layer side adhesive layer has a ~~high~~ higher glass transition temperature than an operating temperature of the flexible printed circuit board, and

wherein a reciprocation number N indicating a bending life of the flexible printed circuit board is at least ten million times at 60°C.

Claim 2. (Original) A flexible printed circuit board according to claim 1, wherein the glass transition temperature is 60°C or higher.

Claim 3. (Original) A flexible printed circuit board according to claim 1, wherein the glass transition temperature is 80°C or higher.

Claim 4. (Original) A flexible printed circuit board according to claim 1, wherein at least one of the base film side adhesive layer and the cover layer side adhesive layer is made of an epoxy resin adhesive.

Claim 5. (Cancelled Without Prejudice)

Claim 6. (Previously Amended) A flexible printed circuit board according to claim 1, wherein a reciprocation number N indicating a bending life of the flexible printed circuit board is between a million times and ten million times at 80°C.

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Claim 7. (Original) A flexible printed circuit board comprising a base film; a base film side adhesive layer provided on the base film; a metal foil layer on which pattern circuit is formed, provided on the base film side adhesive layer; and a cover layer side adhesive layer provided on the metal foil layer,

wherein at least one of the base film side adhesive layer and the cover layer side adhesive layer has a higher glass transition temperature than an operating temperature of the flexible printed circuit board, and

wherein a reciprocation number N indicating a bending life of the flexible printed circuit board is between a million times and ten million times at 80°C.

Claim 8. (Original) A flexible printed circuit board according to claim 7, wherein the glass transition temperature is 60°C or higher.

Claim 9. (Original) A flexible printed circuit board according to claim 7, wherein the glass transition temperature is 80°C or higher.

Claim 10. (Original) A flexible printed circuit board according to claim 7, wherein at least one of the base film side adhesive layer and the cover layer side adhesive layer is made of an epoxy resin adhesive.

Claim 11. (New) A flexible printed circuit board according to claim 1, wherein at least one of the base film side adhesive layer and the cover layer side adhesive layer has a storage modulus of 0.1 GPa or more.

Claim 12. (New) A flexible printed circuit board according to claim 11, wherein the glass transition temperature of at least one of the base film side adhesive layer and the cover layer side adhesive layer is 117°C or lower.

Claim 13. (New) A flexible printed circuit board according to claim 1, wherein the glass transition temperature of at least one of the base film side adhesive layer and the cover layer side adhesive layer is 117°C or lower.

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Claim 14. (New) A flexible printed circuit board according to claim 7, wherein at least one of the base film side adhesive layer and the cover layer side adhesive layer has a storage modulus of 0.1 GPa or more.

Claim 15. (New) A flexible printed circuit board according to claim 14, wherein the glass transition temperature of at least one of the base film side adhesive layer and the cover layer side adhesive layer is 117°C or lower.

Claim 16. (New) A flexible printed circuit board according to claim 7, wherein the glass transition temperature of at least one of the base film side adhesive layer and the cover layer side adhesive layer is 117°C or lower.